



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR TSSOP14

STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
HAST	165	16500	130 °C, 85 % RH	0	0.00
Pressure Pot	165	16500	121 °, 15 PSIG	0	0.00
Solderability	45	360	883 M2003	0	0.00
Temp Cycle	185	82900	- 65 °C to 150 °C	0	0.00